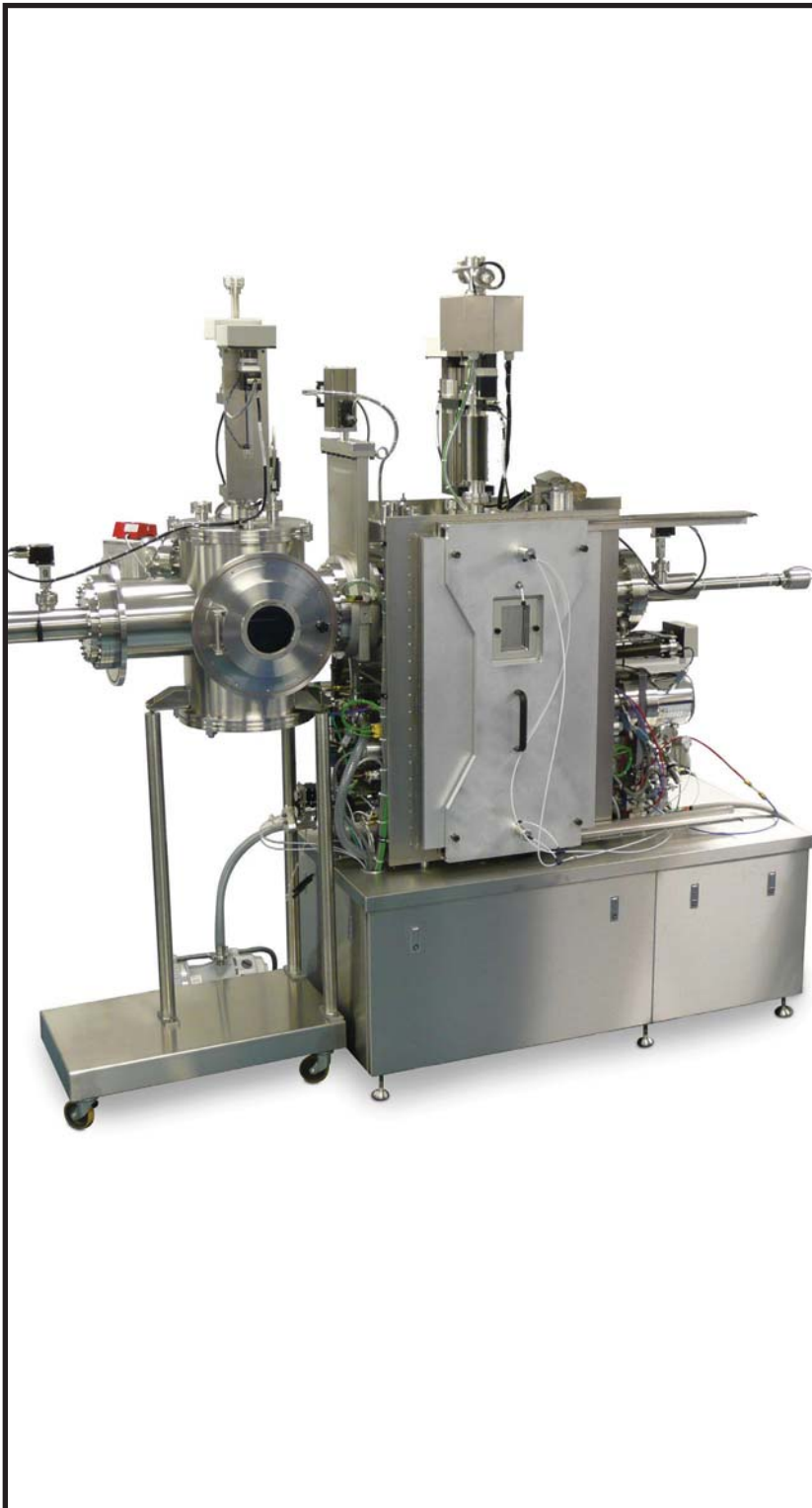


# Super SPECTROS<sup>®</sup>

## Organic Material Deposition System



**Kurt J. Lesker**<sup>®</sup>  
Company

**PROCESS EQUIPMENT**<sup>™</sup>  
DIVISION

### Applications

- Organic Electronics and Photovoltaics (OPV)
- OLED Lighting and Displays
- Integrated Smart Systems
- Metal Cathode Deposition
- Thin Film Batteries
- MEMS/NEMS

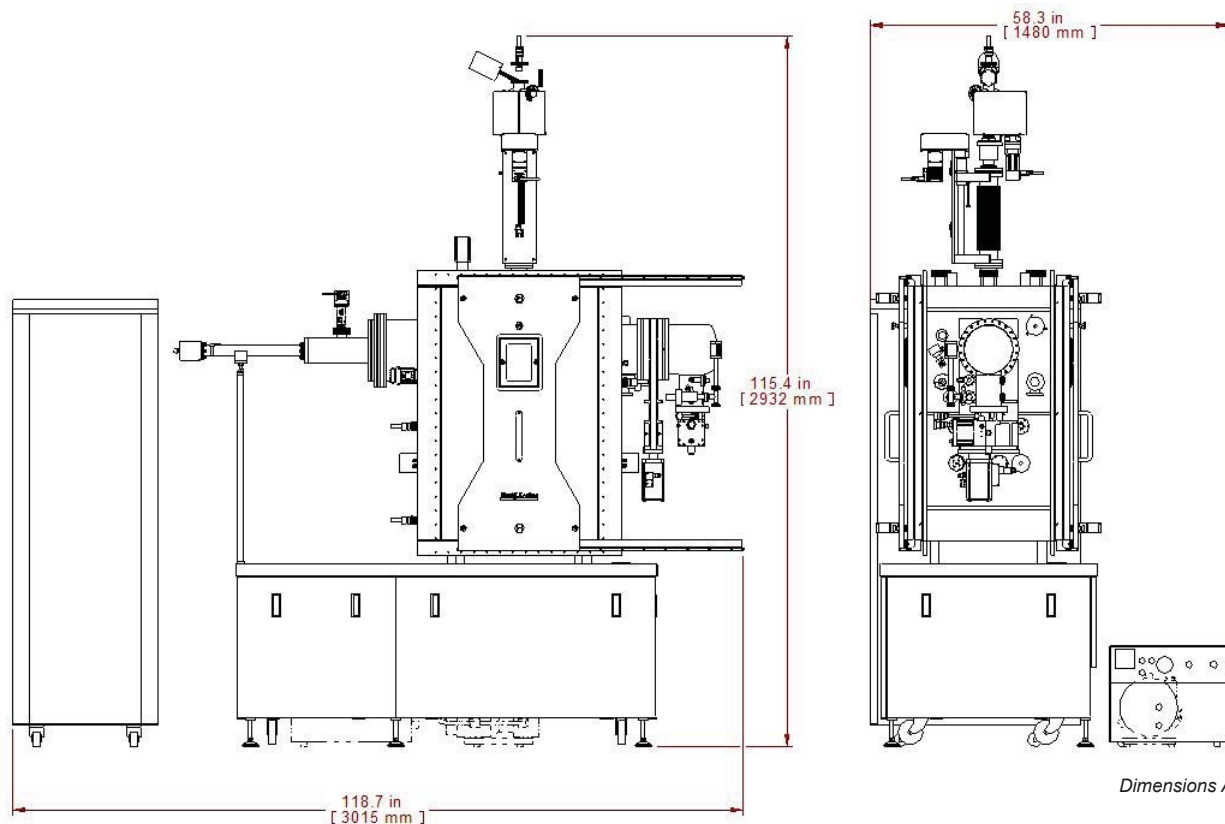
### Features

- Optimized for organic material deposition
- Up to 12 LTE sources; 1cc, 10cc or 35cc capacity
- Host to dopant ratio 100:0.1
- Up to 4 thermal evaporation sources
- Substrate shutter
- Automatic substrate, mask storage and exchange
- Pyrometer port
- Glovebox interfaceable design with sliding front door and hinged rear door
- KJLC eKlipse control software
- Rate control resolution 0.05Å/s
- Recipe based PC based system controls
- Cryopump high vacuum pumping
- 2-position gate valve

### Options

- Wedge tool for shaped film growth
- Co-deposition
- Electron beam source
- Twelve source thermal evaporation source array
- Caesium, Selenium, or HTE source
- Load lock chamber
- Plasma clean
- 3-position gate valve
- In-situ source material replenishment
- Substrate rotation, heating and cooling
- KJLC adaptor box and 2-port or 4-port glovebox
- Turbomolecular pumping
- Datalogging

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## Specifications

Process Chamber	UHV grade, 304 stainless steel, nominally 24" wide x 24" deep by 40" tall
Framework	Steel construction, enclosed panel base with open chamber access, fully enclosed electronics cabinet
Vacuum Pumping	Brooks 1500 l/s cryo pump with oil-free backing pump standard ( $8 \times 10^{-8}$ mbar base pressure)
Vacuum Valves	VAT 2-position pneumatic HV valve. Optional VAT 3-position pneumatic HV valve. All others are KJLC HV valves
Pressure Measurement	Oerlikon Leybold wide range ( $10^{-1}$ - $10^{-10}$ mbar), readout on system control panel
Vacuum Interlocks and Venting	Automatically sequenced vent control & vacuum interlock for process chamber
Deposition Uniformity	$\leq \pm 5\%$ on a 10" (250mm) diameter or 8" (200mm) x 8" (200mm) Si wafer with a 5mm edge exclusion as measured on an AlQ3 or Al film of >200nm thick
Low Temperature Source	KJLC design low temperature evaporation (LTE) source for controlled deposition of materials up to 600°C
Substrate Platen	Platen for up to 10" (250mm) diameter or 8" (200mm) x 8" (200mm), available with 20rpm rotation, substrate heating up to 350°C, cooling to -10°C, and substrate bias. 5-shelf cassette for substrate and mask exchange
Film Thickness Control	Film thickness and deposition rate control enabled via system software and controller (no 3 <sup>rd</sup> party hardware required).
System Control	KJLC eKlipse software PC-based HMI manual computer control, with optional recipe control and datalogging
Required Power (typical, based on options)	400VAC, 3Ø, 32A, 50/60Hz, 5-wire (3Ph+N+E)
Compliance	CE, optional CSA and UL
Warranty	12 months upon receipt, extended warranty is available at additional cost

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